

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Dipankar Bhattacharya</td> <td>02/14/2011</td> </tr> <tr> <td>Ashish V. Shukla</td> <td>02/14/2011</td> </tr> <tr> <td>John Christopher Kriz</td> <td>02/14/2011</td> </tr> <tr> <td>Makeshwar Kothandaraman</td> <td>02/16/2011</td> </tr> </tbody> </table>		Name	Execution Date	Dipankar Bhattacharya	02/14/2011	Ashish V. Shukla	02/14/2011	John Christopher Kriz	02/14/2011	Makeshwar Kothandaraman	02/16/2011
Name	Execution Date										
Dipankar Bhattacharya	02/14/2011										
Ashish V. Shukla	02/14/2011										
John Christopher Kriz	02/14/2011										
Makeshwar Kothandaraman	02/16/2011										
RECEIVING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>LSI Corporation</td> </tr> <tr> <td>Street Address:</td> <td>1621 Barber Lane</td> </tr> <tr> <td>City:</td> <td>Milpitas</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95035</td> </tr> </table>		Name:	LSI Corporation	Street Address:	1621 Barber Lane	City:	Milpitas	State/Country:	CALIFORNIA	Postal Code:	95035
Name:	LSI Corporation										
Street Address:	1621 Barber Lane										
City:	Milpitas										
State/Country:	CALIFORNIA										
Postal Code:	95035										
PROPERTY NUMBERS Total: 1											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th style="width: 70%;">Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13030278</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13030278						
Property Type	Number										
Application Number:	13030278										
CORRESPONDENCE DATA											
<p>Fax Number: (631)239-1066</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 631-656-4966</p> <p>Email: docket@oeklaw.com</p> <p>Correspondent Name: Wayne L. Ellenbogen</p> <p>Address Line 1: Otterstedt, Ellenbogen & Kammer, LLP</p> <p>Address Line 2: P.O. Box 98</p> <p>Address Line 4: East Northport, NEW YORK 11731</p>											
ATTORNEY DOCKET NUMBER:	L10-0324US1										
NAME OF SUBMITTER:	Wayne L. Ellenbogen										
Total Attachments: 5											

OP \$40.00 13030278

501443001

PATENT
REEL: 025831 FRAME: 0743

source=115-73_ASM#page1.tif
source=115-73_ASM#page2.tif
source=115-73_ASM#page3.tif
source=115-73_ASM#page4.tif
source=115-73_ASM#page5.tif

ASSIGNMENT AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We, **Dipankar Bhattacharya, Ashish V. Shukla, John Christopher Kriz, and Makeswar Kothandaraman**, hereby sell, assign and transfer to **LSI Corporation**, a corporation of the State of Delaware, having an office at 1621 Barber Lane, Milpitas, CA 95035, United States of America, and its successors, assigns and legal representatives (collectively "Assignee"), the entire right, title and interest, for the United States and all foreign countries, in and to any and all inventions and improvements ("Inventions") related to **IMPEDANCE COMPENSATION IN A BUFFER CIRCUIT**, as described in an application for Letters Patent of the United States of America filed on February 18, 2011 and assigned Serial No. 13 / 030,278, or if not identified here by filing date and serial number, executed on even date with the execution of this Assignment Agreement, and in and to the application and all divisional, continuing, substitute, renewal, reissue and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries for the Inventions, and all the rights and privileges under any and all Letters Patent that may be granted therefore including any reissues and extensions thereof.

I/We agree that when requested I/we will, without charge to Assignee but at its expense, sign all papers, take all rightful oaths, make all rightful declarations and do all acts which may be necessary, desirable or convenient for securing and maintaining patents or other forms of protection for the Inventions in any and all countries and for vesting title thereto in Assignee.

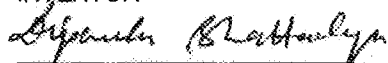
I/We authorize and empower Assignee to make applications for patent or other form of protection for the Inventions in Assignee's own name in any and all countries, and to invoke and claim for any application for patent or other form of protection for the Inventions filed by Assignee the benefit of all rights of priority provided by any and all treaties, conventions or agreements without further written or oral authorization.

I/We hereby consent that a copy of this Assignment Agreement shall be deemed a full legal and formal equivalent of any assignment, consent to file or similar document which may be required in any country for any purpose, including proof of the right of Assignee to apply for patent or other form of protection for the Inventions and to claim the aforesaid benefit of the right of priority.

I/We authorize attorneys for Assignee to insert the filing date and serial number into this Assignment Agreement after the application for Letters Patent has been filed and a serial number has been assigned to such application.

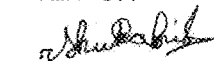
IN WITNESS WHEREOF, I/we have hereunto signed my/our name(s) on the day and year set forth below.

INVENTOR

**Dipankar Bhattacharya**02/14/2011

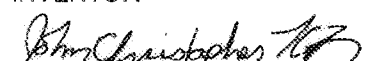
Date

INVENTOR

**Ashish V. Shukla**02/14/2011

Date

INVENTOR

**John Christopher Kriz**2/14/11

Date

INVENTOR

Makeswar Kothandaraman

Date

File No.: L10-0324US1

Rev1: 10/08/2009

ACKNOWLEDGMENT

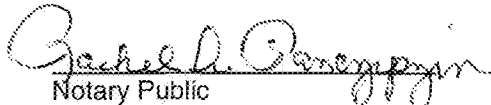
State of Pennsylvania

County of Lehigh

On this 14 day of February, 2011, before me personally appeared
Ashish V. Shukla

known to me to be the individual described in and who executed the foregoing instrument, and
acknowledged execution of the same.

In witness hereof, I hereunto set my hand and official seal.

 (Seal)
Notary Public

COMMONWEALTH OF PENNSYLVANIA

Notarial Seal
Rachel A. Panczyzain, Notary Public
Hanover Twp., Lehigh County
My Commission Expires July 14, 2013
Member, Pennsylvania Association of Notaries

ACKNOWLEDGMENT

State of Pennsylvania

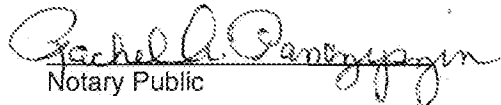
County of Lehigh

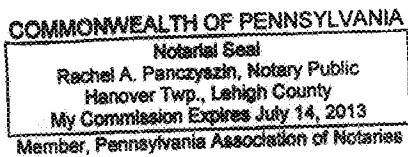
On this 14 day of February, 2011, before me personally appeared

Dipankar Bhattacharya

known to me to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same.

In witness hereof, I hereunto set my hand and official seal.

 (Seal)
Notary Public



ACKNOWLEDGMENT

State of Pennsylvania

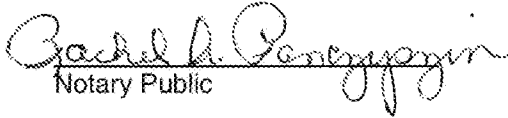
County of Lehigh

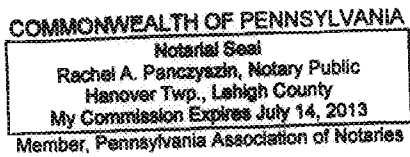
On this 14 day of February, 2011, before me personally appeared

John Christopher Kriz

known to me to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same.

In witness hereof, I hereunto set my hand and official seal.

 (Seal)
Notary Public



ASSIGNMENT AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We, **Dipankar Bhattacharya, Ashish V. Shukla, John Christopher Kriz, and Makeswar Kothandaraman**, hereby sell, assign and transfer to LSI Corporation, a corporation of the State of Delaware, having an office at 1621 Barber Lane, Milpitas, CA 95035, United States of America, and its successors, assigns and legal representatives (collectively "Assignee"), the entire right, title and interest, for the United States and all foreign countries, in and to any and all inventions and improvements ("Inventions") related to **IMPEDANCE COMPENSATION IN A BUFFER CIRCUIT**, as described in an application for Letters Patent of the United States of America filed on February 18, 2011 and assigned Serial No. 13 / 030,278, or if not identified here by filing date and serial number, executed on even date with the execution of this Assignment Agreement, and in and to the application and all divisional, continuing, substitute, renewal, reissue and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries for the Inventions, and all the rights and privileges under any and all Letters Patent that may be granted therefore including any reissues and extensions thereof.

I/We agree that when requested I/we will, without charge to Assignee but at its expense, sign all papers, take all rightful oaths, make all rightful declarations and do all acts which may be necessary, desirable or convenient for securing and maintaining patents or other forms of protection for the Inventions in any and all countries and for vesting title thereto in Assignee.

I/We authorize and empower Assignee to make applications for patent or other form of protection for the Inventions in Assignee's own name in any and all countries, and to invoke and claim for any application for patent or other form of protection for the Inventions filed by Assignee the benefit of all rights of priority provided by any and all treaties, conventions or agreements without further written or oral authorization.

I/We hereby consent that a copy of this Assignment Agreement shall be deemed a full legal and formal equivalent of any assignment, consent to file or similar document which may be required in any country for any purpose, including proof of the right of Assignee to apply for patent or other form of protection for the Inventions and to claim the aforesaid benefit of the right of priority.

I/We authorize attorneys for Assignee to insert the filing date and serial number into this Assignment Agreement after the application for Letters Patent has been filed and a serial number has been assigned to such application.

IN WITNESS WHEREOF, I/we have hereunto signed my/our name(s) on the day and year set forth below.

INVENTOR

INVENTOR

INVENTOR

Dipankar BhattacharyaAshish V. ShuklaJohn Christopher KrizDateDateDate

INVENTOR

Makeswar KothandaramanMakeswar KothandaramanFeb 16th, 2011Date

File No.: L10-0324US1

Rev1: 10/06/2009